

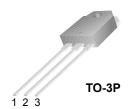
FFA120UP60DN Ultrafast Recovery Power Rectifier

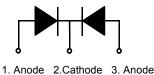
Features

- · High voltage and high reliability
- · High speed switching
- · Low forward voltage

Applications

- · General purpose
- · Switching mode power supply
- Free-wheeling diode for motor application
- · Power switching circuits





Absolute Maximum Ratings (per diode) Ta = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------------------------|---|--------------|-------|
| V_{RRM} | Peak Repetitive Reverse Voltage | 600 | V |
| I _{F(AV)} | Average Rectified Forward Current @ T _C = 50°C | 120 | А |
| I _{FSM} | Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave | 360 | А |
| T _J , T _{STG} | Operating Junction and Storage Temperature | - 65 to +150 | °C |

Thermal Characteristics T_a = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------|--|-------|-------|
| $R_{\theta JC}$ | Maximum Thermal Resistance, Junction to Case | 0.88 | °C/W |

Electrical Characteristics (per diode) T_a = 25°C unless otherwise noted

| Symbol | Parameter | | Min. | Тур. | Max. 2.2 2.0 | Units V |
|---|---|---|-------------|-------------|--------------------|---------------|
| V _{FM} * | Maximum Instantaneous Forward Voltage $I_F = 60A$ $I_F = 60A$ | T _C = 25 °C T _C = 100 °C | | | | |
| I _{RM} * | Maximum Instantaneous Reverse Current @ rated V _R | T _C = 25 °C T _C = 100 °C | | - - | 25 250 | μΑ |
| t _{rr} I _{rr} Q _{rr} | Maximum Reverse Recovery Time Maximum Reverse Recovery Current Maximum Reverse Recovery Charge (I _F =60A, di/dt = 200A/μs) | | - - - | - - - | 90 9 405 | ns A nC |
| W _{AVL} | Avalanche Energy (L = 40mH) | | 20 | - | - | mJ |

^{*} Pulse Test: Pulse Width=300 μ s, Duty Cycle=2%

Typical Performance Characteristics

Figure 1. Typical Forward Voltage Drop vs. Forward Current

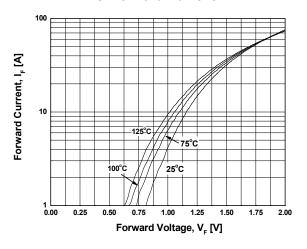


Figure 3. Typical Junction Capacitance

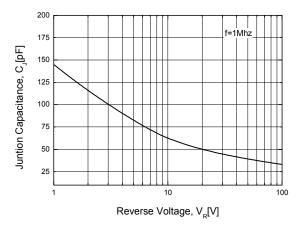


Figure 5. Typical Reverse Recovery Current vs. di/dt

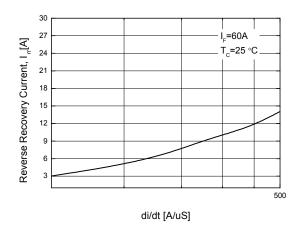


Figure 2. Typical Reverse Current vs. Reverse Voltage

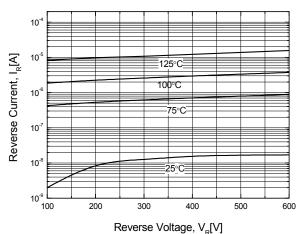


Figure 4. Typical Reverse Recovery Time vs. di/dt

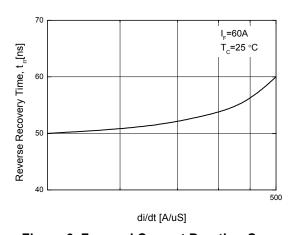
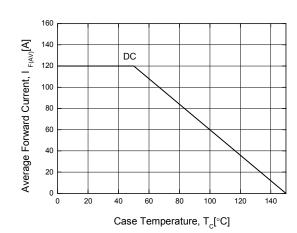


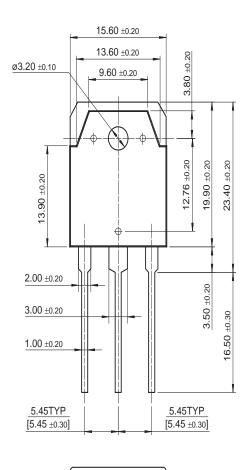
Figure 6. Forward Current Derating Curve

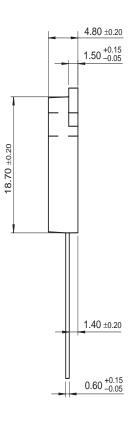


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Mechanical Dimensions

TO-3P





Dimensions in Millimeters

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